

# 1SS120

Silicon Epitaxial Planar Diode for High Speed Switching

# HITACHI

ADE-208-167B (Z)

Rev. 2

Aug. 1995

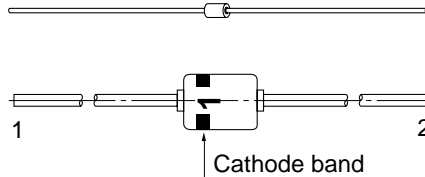
## Features

- Low capacitance. ( $C = 3.0\text{pF max}$ )
- Short reverse recovery time. ( $t_{rr} = 3.5\text{ns max}$ )
- Small glass package (MHD) enables easy mounting and high reliability.

## Ordering Information

Type No.	Cathode band	Mark	Package Code
1SS120	Light Blue	1	MHD

## Outline



1. Cathode
2. Anode

## Absolute Maximum Ratings (Ta = 25°C)

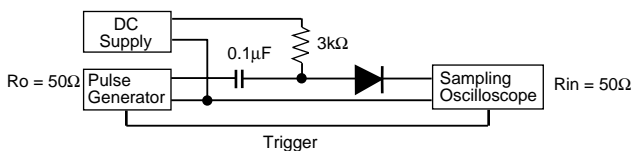
Item	Symbol	Value	Unit
Peak reverse voltage	$V_{RM}$	70	V
Reverse voltage	$V_R$	60	V
Peak forward current	$I_{FM}$	450	mA
Non-Repetitive peak forward surge current	$I_{FSM}^*$	1	A
Average forward current	$I_O$	150	mA
Power dissipation	$P_d$	250	mW
Junction temperature	$T_j$	175	°C
Storage temperature	$T_{stg}$	-65 to +175	°C

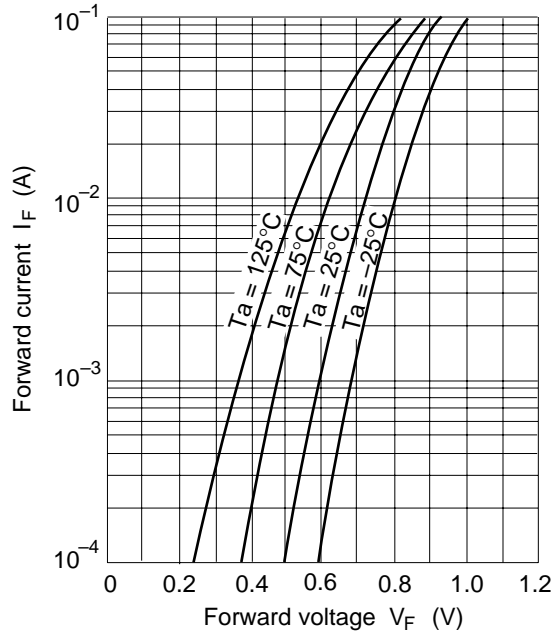
Note: Within 1s forward surge current.

## Electrical Characteristics (Ta = 25°C)

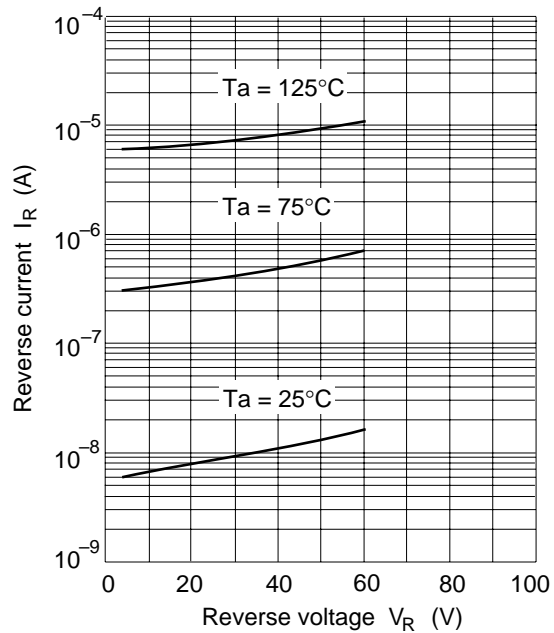
Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	$V_F$	—	—	0.8	V	$I_F = 10\text{mA}$
Reverse current	$I_R$	—	—	0.1	$\mu\text{A}$	$V_R = 60\text{V}$
Capacitance	$C$	—	—	3.0	pF	$V_R = 1\text{V}, f = 1\text{MHz}$
Reverse recovery time	$t_{rr}^*$	—	—	3.5	ns	$I_F = 10\text{mA}, V_R = 6\text{V}, R_L = 50\Omega$

Note: Reverse recovery time test circuit





**Fig.1 Forward current Vs. Forward voltage**



**Fig.2 Reverse current Vs. Reverse voltage**

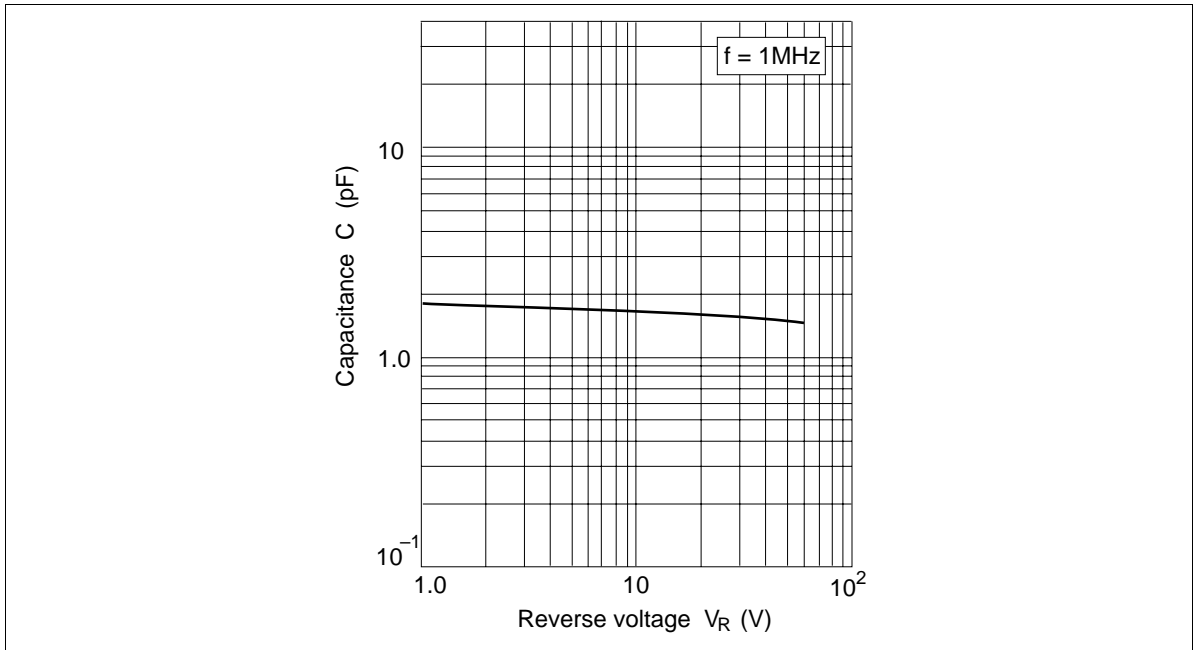
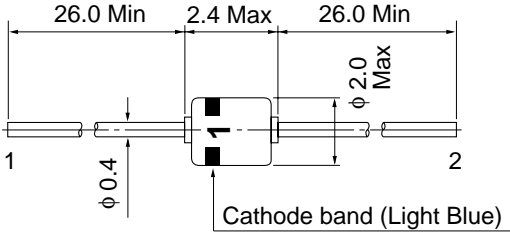


Fig.3 Capacitance Vs. Reverse voltage

Package Dimensions

Unit: mm



- 1 Cathode
- 2 Anode

HITACHI Code	MHD
JEDEC Code	DO-34
EIAJ Code	—
Weight (g)	0.084

## Cautions

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# HITACHI

## Hitachi, Ltd.

Semiconductor & Integrated Circuits.  
Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan  
Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

URL      North America      : <http://semiconductor.hitachi.com/>  
             Europe                 : <http://www.hitachi-eu.com/hel/ecg>  
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## For further information write to:

Hitachi Semiconductor  
(America) Inc.  
179 East Tasman Drive,  
San Jose, CA 95134  
Tel: <1> (408) 433-1990  
Fax: <1>(408) 433-0223

Hitachi Europe GmbH  
Electronic components Group  
Dornacher Straße 3  
D-85622 Feldkirchen, Munich  
Germany  
Tel: <49> (89) 9 9180-0  
Fax: <49> (89) 9 29 30 00

Hitachi Europe Ltd.  
Electronic Components Group.  
Whitebrook Park  
Lower Cookham Road  
Maidenhead  
Berkshire SL6 8YA, United Kingdom  
Tel: <44> (1628) 585000  
Fax: <44> (1628) 778322

Hitachi Asia Pte. Ltd.  
16 Collyer Quay #20-00  
Hitachi Tower  
Singapore 049318  
Tel: 535-2100  
Fax: 535-1533

Hitachi Asia Ltd.  
Taipei Branch Office  
3F, Hung Kuo Building, No.167,  
Tun-Hwa North Road, Taipei (105)  
Tel: <886> (2) 2718-3666  
Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd.  
Group III (Electronic Components)  
7/F., North Tower, World Finance Centre,  
Harbour City, Canton Road, Tsim Sha Tsui,  
Kowloon, Hong Kong  
Tel: <852> (2) 735 9218  
Fax: <852> (2) 730 0281  
Telex: 40815 HITEC HX

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